

Data sheet acquired from Harris Semiconductor SCHS035C – Revised September 2003

CMOS Quad Exclusive-OR Gate

High-Voltage Types (20-Volt Rating)

■ CD4030B types consist of four independent Exclusive-OR gates. The CD4030B provides the system designer with a means for direct implementation of the Exclusive-

The CD4030B types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PW and PWR suffixes).

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (VDD)

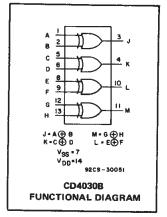
CD4030B Types

Features:

- Medium-speed operation—tpHL, tpLH = 65 ns (typ.) at $V_{DD} = 10 \text{ V, C}_{L} = 50 \text{ pF}$
- 100% tested for quiescent current at 20 V
- Standardized, symmetrical output characteristics
- 5-V, 10-V, and 15-V parametric ratings
- Maximum input current of 1 µA at 18 V over full packagetemperature range; 100 nA at 18 V and 25°C
- Noise margin (over full package-temperature range):

1 V at V_{DD} = 5 V 2 V at V_{DD} = 10 V 2.5 V at V_{DD} = 15 V

■ Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"



Applications:

- Even and odd-parity generators and checkers
- Logical comparators
- Adders/subtractors
- General logic functions

DC INPUT CURRENT, ANY ONE INPUT ±10mA POWER DISSIPATION PER PACKAGE (PD): For T_A = +100°C to +125°C...... Derate Linearity at 12mW/°C to 200mW

Voltages referenced to VSS Terminal)-0.5V to +20V

INPUT VOLTAGE RANGE, ALL INPUTS-0.5V to V_{DD} +0.5V

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

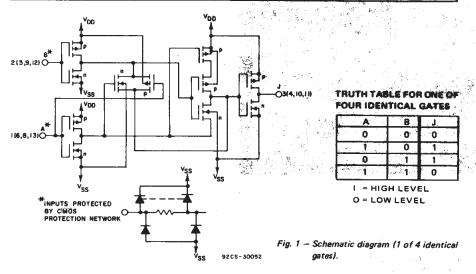
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW OPERATING-TEMPERATURE RANGE (TA).....-55°C to +125°C STORAGE TEMPERATURE RANGE (T_{stg}).....-65°C to +150°C LEAD TEMPERATURE (DURING SOLDERING):

At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max +265°C

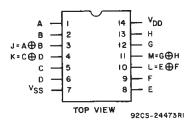
RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIM	:		
CHARACTERISTIC	MIN. MAX.		UNITS	
Supply-Voltage Range (For T _A = Full Package: Temperature Range)	3.	18	V	



TERMINAL DIAGRAM Top View



CD4030B Types

STATIC ELECTRICAL CHARACTERISTICS

CHARAC-	CONI	OITIO	NS	LIMITS AT INDICATED TEMPERATURES (°C)								
TERISTIC	v _o	VIN	v_{DD}						+25	,	T	
	(V)	(V)	(V)	–55	-40	+85	+125	Min.	Тур.	Max.	S	
Quiescent		0,5	5	0.25	0.25	7.5	7.5		0.01	0.25		
Device	_	0,10	10	0.5	0.5	15	15	-	0.01	0.5	μ	
Current, I _{DD}		0,15	15	1	1	30	30	-	0.01	1		
Max.	-	0,20	20	5	5	150	150	_	0.02	5		
Output Low (Sink)	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	_		
Current	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	_		
I _{OL} Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	_		
Output High (Source)	4.6	0,5	5	-0.64	-0.61	0.42	-0.36	-0.51	-1	-	'n	
	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	_	ŀ	
Current,	9.5	0,10	10	-1.6	1.5	-1.1	-0.9	-1.3	-2.6		1	
IOH Min.	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8		1	
Output Voltage:	_	0,5	5		0	.05	_	0	0.05	Γ		
Low-Level,		0,10	10		0	.05	_		0.05]		
VOL Max.	-	0,15	15		0	.05		-	0	0.05],	
Output Voltage:	_	0,5	5		4	.95	4.95	5		1		
High-Level,	_	0,10	10		9	.95		9.95	10	_	1	
V _{OH} Min.	_	0,15	15		14	.95		14.95	15	_	1	
Input Low	0.5,4.5	ı	5		1	.5		_	_	1.5		
Voltage,	1,9	-	10			3		_	-	3		
V _{IL} Max.	1.5,13.5	-	15			4		-	_	4	١,	
Input High	0.5,4.5	_	5			3.5		3.5	_	_]	
Voltage,	1,9	_	10			7	J	. 7		-		
V _{1H} Min.	1.5,13.5	_	15			11		11	_			
Input Current IN Max.	_	0,18	18	±0.1	±0.1	±1	±1	_	±10 ⁻⁵	±0.1	4	

DYNAMIC ELECTRICAL CHARACTERISTICS at T $_A$ = 25°C; Input t $_r$, t $_f$ = 20 ns, C $_L$ = 50 pF, R $_L$ = 200 K Ω

	CONDITIONS		UNITS				
CHARACTERISTIC	V _{DD}	LIM					
		(V)	Тур.	Max.			
Propagation Delay Time,	-	5	140	280			
	tPLH, tPHL	10	65	130	ns		
		15	50	100			
		5	100	200	ns		
Transition Time,	^t THL ^{, t} TLH	10	50	100			
		15	40	80			
Input Capacitance,	CIN	Any Input	5	7.5	ρF		

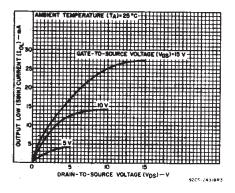


Fig. 2 — Typical output low (sink) current characteristics.

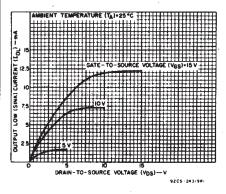


Fig. 3 – Minimum output low (sink) current characteristics.

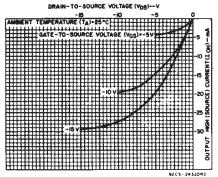


Fig. 4 — Typical output high (source) current characteristics.

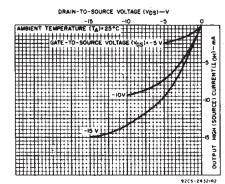


Fig. 5 – Minimum output high (source) current characteristics.

CD4030B Types

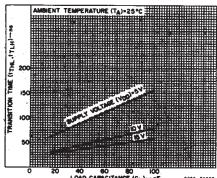


Fig. 6 — Typical transition time as a function of load capacitance.

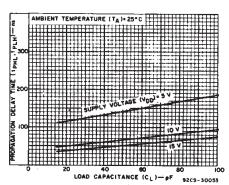


Fig. 7 — Typical propagation delay time as a function of load capacitance.

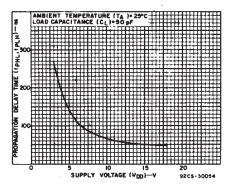


Fig. 8 — Typical propagation delay time as a function of supply voltage.

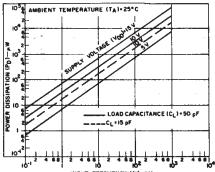


Fig. 9 — Typical dynamic power dissipation as a function of input frequency.

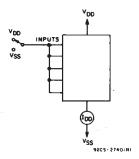


Fig. 10 - Quiescent-device current test circuit.

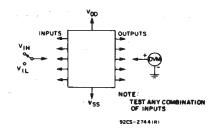


Fig. 11 — Input-voltage test circuit.

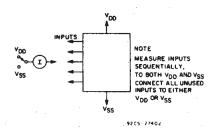


Fig. 12 - Input-current test circuit.

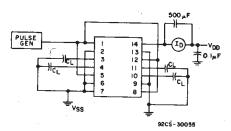
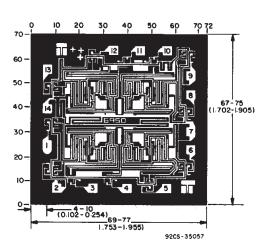


Fig. 13 – Dynamic power dissipation test circuit.



Dimensions and pad layout for CD4030BH.

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CD4030BE	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4030BE	Samples
CD4030BEE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4030BE	Samples
CD4030BF	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD4030BF	Samples
CD4030BF3A	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD4030BF3A	Samples
CD4030BM	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4030BM	Samples
CD4030BM96	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4030BM	Samples
CD4030BM96G4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4030BM	Samples
CD4030BNSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4030B	Samples
CD4030BNSRG4	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CD4030B	Samples
CD4030BPW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM030B	Samples
CD4030BPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	CM030B	Samples
JM38510/05353BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 05353BCA	Samples
M38510/05353BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 05353BCA	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

PACKAGE OPTION ADDENDUM

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Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD4030B, CD4030B-MIL:

Catalog: CD4030B

Military: CD4030B-MIL

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4030BM96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4030BM96G4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CD4030BNSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4030BPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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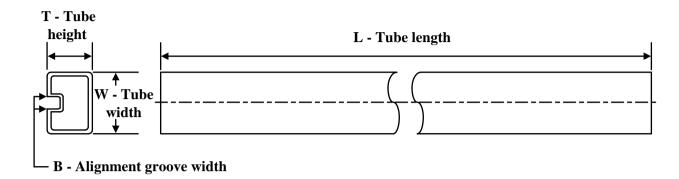
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4030BM96	SOIC	D	14	2500	356.0	356.0	35.0
CD4030BM96G4	SOIC	D	14	2500	356.0	356.0	35.0
CD4030BNSR	SO	NS	14	2000	356.0	356.0	35.0
CD4030BPWR	TSSOP	PW	14	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD4030BE	N	PDIP	14	25	506	13.97	11230	4.32
CD4030BE	N	PDIP	14	25	506	13.97	11230	4.32
CD4030BEE4	N	PDIP	14	25	506	13.97	11230	4.32
CD4030BEE4	N	PDIP	14	25	506	13.97	11230	4.32
CD4030BM	D	SOIC	14	50	506.6	8	3940	4.32
CD4030BPW	PW	TSSOP	14	90	530	10.2	3600	3.5

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
 - Sody length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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